

IN THE SPECIFICATION:

Please amend the specification as follows:

Paragraph beginning on page 6, at line 16, has been amended as follows:

Afterward, in step 450, the reporter transmitter 180 next forwards the thermal data simulation report to the user through internet 300. FIGURE 4 shows a report the outputs of the system 100 according to the present invention. The thermal data ~~includes~~ includes: (1) a temperature variance from a junction temperature to an ambient temperature per unit power dissipation θ_{ja} , $\theta_{ja} = (T_j - T_a)/P$, wherein T_j indicates the junction temperature and the temperature, T_a is the ambient temperature: temperature, and P indicates the power dissipation dissipation; (2) a temperature variance from the junction temperature to a package top center temperature Ψ_{jt} , $\Psi_{jt} = (T_j - T_t)/P$, wherein T_t indicates the package top center temperature temperature; and (3) a temperature variance from the junction temperature to a case temperature per unit power dissipation θ_{jc} , $\theta_{jc} = (T_j - T_c)/P$, wherein T_c indicates the case temperature. The thermal data also includes the parameter of the percentage of heat dissipated from PCB (print circuit board), from the package top and from others.